Serial-In Parallel-Out Shift Register

The SN74LS164 is a high speed 8-Bit Serial-In Parallel-Out Shift Register. Serial data is entered through a 2-Input AND gate synchronous with the LOW to HIGH transition of the clock. The device features an asynchronous Master Reset which clears the register setting all outputs LOW independent of the clock. It utilizes the Schottky diode clamped process to achieve high speeds and is fully compatible with all ON Semiconductor TTL products.

- Typical Shift Frequency of 35 MHz
- Asynchronous Master Reset
- Gated Serial Data Input
- Fully Synchronous Data Transfers
- Input Clamp Diodes Limit High Speed Termination Effects
- ESD > 3500 Volts

GUARANTEED OPERATING RANGES

Symbol	Parameter	Min	Тур	Max	Unit
VCC	Supply Voltage	4.75	5.0	5.25	V
T _A	Operating Ambient Temperature Range	0	25	70	°C
IOH	Output Current – High			-0.4	mA
lOL	Output Current – Low			8.0	mA



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LOW POWER SCHOTTKY



PLASTIC N SUFFIX CASE 646



SOIC D SUFFIX CASE 751A



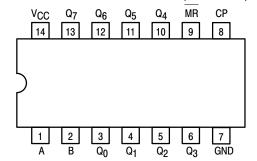
SOEIAJ M SUFFIX CASE 965

ORDERING INFORMATION

Device	Package	Shipping
SN74LS164N	14 Pin DIP	2000 Units/Box
SN74LS164D	SOIC-14	55 Units/Rail
SN74LS164DR2	SOIC-14	2500/Tape & Reel
SN74LS164M	SOEIAJ-14	See Note 1
SN74LS164MEL	SOEIAJ-14	See Note 1

 For ordering information on the EIAJ version of the SOIC package, please contact your local ON Semiconductor representative.

CONNECTION DIAGRAM DIP (TOP VIEW)



NOTE:

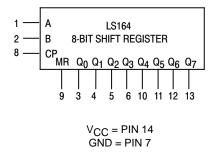
The Flatpak version has the same pinouts (Connection Diagram) as the Dual In-Line Package.

		LOADING	(Note a)
PIN NAMES		HIGH	LOW
A, B <u>CP</u> MR Q ₀ - Q ₇	Data Inputs Clock (Active HIGH Going Edge) Input Master Reset (Active LOW) Input Outputs	0.5 U.L. 0.5 U.L. 0.5 U.L. 10 U.L.	0.25 U.L. 0.25 U.L. 0.25 U.L. 5 U.L.

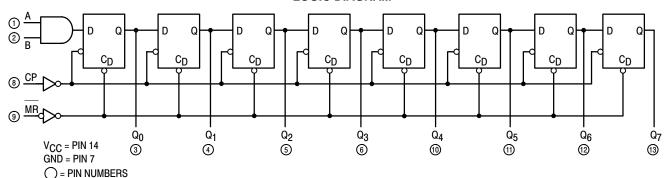
NOTES:

a) 1 TTL Unit Load (U.L.) = 40 μA HIGH/1.6 mA LOW.

LOGIC SYMBOL



LOGIC DIAGRAM



FUNCTIONAL DESCRIPTION

The LS164 is an edge-triggered 8-bit shift register with serial data entry and an output from each of the eight stages. Data is entered serially through one of two inputs (A or B); either of these inputs can be used as an active HIGH Enable for data entry through the other input. An unused input must be tied HIGH, or both inputs connected together.

Each LOW-to-HIGH transition on the Clock (CP) input shifts data one place to the right and enters into Q0 the logical AND of the two data inputs (A•B) that existed before the rising clock edge. A LOW level on the Master Reset (MR) input overrides all other inputs and clears the register asynchronously, forcing all Q outputs LOW.

MODE SELECT — TRUTH TABLE

OPERATING	INPUTS			OUTPUTS		
MODE	MR	Α	В	Q_0	Q ₁ –Q ₇	
Reset (Clear)	L	Х	Х	L	L-L	
Shift	H H H	l h h	l h l h	L L H	q0 - q6 q0 - q6 q0 - q6 q0 - q6	

L (I) = LOW Voltage Levels H (h) = HIGH Voltage Levels

X = Don't Care

 q_n = Lower case letters indicate the state of the referenced input or output one set-up time prior to the LOW to HIGH clock transition.

DC CHARACTERISTICS OVER OPERATING

TEMPERATURE RANGE (unless otherwise specified)

		Limits					
Symbol	Parameter	Min	Тур	Max	Unit	Test C	onditions
VIH	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs	
VIL	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs	
VIK	Input Clamp Diode Voltage		-0.65	-1.5	V	V _{CC} = MIN, I _{IN} = -18 mA	
VOH	Output HIGH Voltage	2.7	3.5		V	V _{CC} = MIN, I _{OH} = MAX, V _{IN} = V _{IH} or V _{IL} per Truth Table	
.,	0		0.25	0.4	V	I _{OL} = 4.0 mA	V _{CC} = V _{CC} MIN,
VOL	Output LOW Voltage		0.35	0.5	V	I _{OL} = 8.0 mA	V _{IN} = V _{IH} or V _{IL} per Truth Table
I	lament I II Old Commant			20	μΑ	V _{CC} = MAX, V _{IN}	= 2.7 V
lΗ	Input HIGH Current			0.1	mA	V _{CC} = MAX, V _{IN} = 7.0 V	
IIL	Input LOW Current			-0.4	mA	V _{CC} = MAX, V _{IN} = 0.4 V	
los	Short Circuit Current (Note 2)	-20		-100	mA	V _{CC} = MAX	
Icc	Power Supply Current			27	mA	V _{CC} = MAX	

^{2.} Not more than one output should be shorted at a time, nor for more than 1 second.

AC CHARACTERISTICS $(T_A = 25^{\circ}C)$

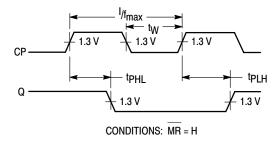
			Limits			
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
f _{MAX}	Maximum Clock Frequency	25	36		MHz	
^t PHL	Propagation Delay MR to Output Q		24	36	ns	V _{CC} = 5.0 V C _L = 15 pF
^t PLH ^t PHL	Propagation Delay Clock to Output Q		17 21	27 32	ns	o <u>l</u> 10 p.

AC SETUP REQUIREMENTS $(T_A = 25^{\circ}C)$

		Limits				
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
tW	CP, MR Pulse Width	20			ns	
t _S	Data Setup Time	15			ns	V 50V
th	Data Hold Time	5.0			ns	V _{CC} = 5.0 V
t _{rec}	MR to Clock Recovery Time	20			ns	

AC WAVEFORMS

*The shaded areas indicate when the input is permitted to change for predictable output performance.



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Figure 1. Clock to Output Delays and Clock Pulse Width

Figure 2. Master Reset Pulse Width, Master Reset to Output Delay and Master Reset to Clock Recovery Time

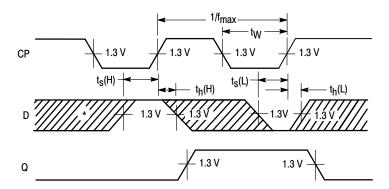
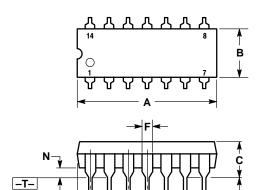


Figure 3. Data Setup and Hold Times

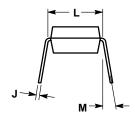
PACKAGE DIMENSIONS

N SUFFIX PLASTIC PACKAGE CASE 646-06 ISSUE M



0.13 (0.005) M

SEATING PLANE

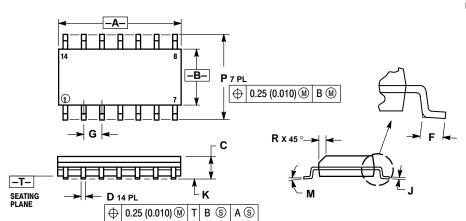


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS
DIM	MIN	MIN MAX		MAX
Α	0.715	0.770	18.16	18.80
В	0.240	0.260	6.10	6.60
С	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100	BSC	2.54	BSC
Н	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
M		10°		10°
N	0.015	0.039	0.38	1.01

PACKAGE DIMENSIONS

D SUFFIX PLASTIC SOIC PACKAGE CASE 751A-03 ISSUE F



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

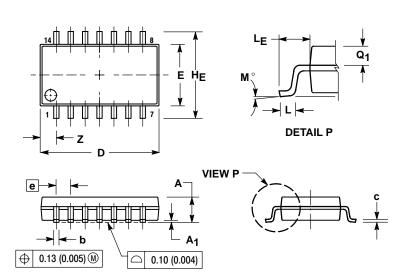
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MIN MAX		MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7°	0 °	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

M SUFFIX

SOEIAJ PACKAGE CASE 965-01 **ISSUE O**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003)
 TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION.
 DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
Α ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050 BSC	
ΗE	7.40	8.20	0.291	0.323
0.50	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10°	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z		1.42		0.056

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